

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("4872463").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/29 17:47
S2	2	("7354654").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/29 17:59
S3	0	(Process and resin and mold and resist and metal and layers and solubility near2 control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:06
S4	0	(method and resin and mold and resist and metal and layers and solubility near2 control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:16
S5	0	(resin and mold and resist and metal and layers and solubility near2 control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:16
S6	1	(resin and resist and metal and layers and solubility near2 control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:17
S7	1	(resist and metal and layers and solubility near2 control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:22

S8	1	(mold and metal and layers and solubility near2 control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:22
S9	1	(mold and metal and layers and solubility near control).ab.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:23
S10	2686	430/322.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:23
S11	1283	S10 and metal	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:23
S12	882	S11 and resist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:23
S13	83	S12 and mold	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 18:23
S14	14	((("5407782") or ("4657843") or ("6881358") or ("5676906") or ("5209688") or ("5580511") or ("6472459"))).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/30 09:33
S15	16	((("5407782") or ("4657843") or ("6881358") or ("5676906") or ("5209688") or ("5580511") or ("6472459") or ("5716741"))).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/04/30 09:35

S16	244210	PMER near S14 developer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 09:59
S17	7	PMER near1 developer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 09:59
S18	22	"5338626"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 11:12
S19	15	"5139922"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/30 14:35
S20	128175	nishi.in. or kitani.in. yanagawa.in. or fukuda.in. or nagayama.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:44
S21	14307	S20 and resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:44
S22	996	S21 and resist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:44
S23	133	S22 and solubility	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:44

S24	124	S23 and (heat or thermal or irradiation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:45
S25	5	"2005016370"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:56
S26	135477	nakajima.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:56
S27	2	S26 and "20050167370"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 08:57
S28	14	"4859573"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 09:16
S29	10	"5716741"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 09:42
S30	12	("5234571" "5260175" "5311604" "5529681").PN. OR ("5716741").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/21 09:45
S31	1	(process or method) and (forming and resist and pattern and substrate and metal and resin and plurality and resist and layers upper and resist and lower and solubility and developer).dm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:05

S32	551	(process or method) and (forming and resist and pattern and substrate and metal and resin and plurality and resist and layers upper and resist and lower and solubility and developer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:06
S33	1678444	stamp or master or mold	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:42
S34	5715	S33 and (resist near1 layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:42
S35	2974	S34 and ((plurality or "more than one" or multiple) same layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:43
S36	1510	S35 and resin	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:43
S37	144	S36 and solubility	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/05/21 10:47
S38	15	"5656414"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/21 11:56

5/ 22/ 2009 10:18:40 AM

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